

WHAT IS CLAIMED IS

1. An electroplating device comprising an anode which is inserted through and disposed in a hole provided in a work and communicating with the outside, and a member for rotating said work about its center axis and supplying a plating electric current to said work.

2. An electroplating device comprising an anode which is inserted through and disposed in a hole provided in a work and communicating with the outside, a member for rotating said work about its center axis, and a member for supplying a plating electric current to said work.

3. An electroplating device comprising an anode which is inserted through and disposed in a hole provided in a work and communicating with the outside, a driving roller made of a metal and adapted to abut against the outer surface of said work to support said work for rotating said work about its center axis and supplying a plating electric current to said work, and a follower roller adapted to abut against the outer surface of said work to support said work.

4. An electroplating device comprising an anode which is inserted through and disposed in a hole provided in a work and communicating with the outside, a driving roller adapted to abut against the outer surface of said work to support said work for rotating said work about its center axis, and a follower roller made of a metal and adapted to abut against the outer surface of said work to support said work for supplying a plating electric current

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to said work.

5. An electroplating device comprising an anode which is inserted through and disposed in a hole provided in a work and communicating with the outside, and a means for allowing a plating solution within said hole in said work to flow.

6. An electroplating device according to claim 1 or 2, further including a means for allowing a plating solution within said hole in said work to flow.

7. A process for electroplating a work having a hole communicating with the outside, using an electroplating device according to claim 1 or 2.

8. A process for electroplating a work according to claim 7, wherein said work having the hole communicating with the outside is a ring-shaped work.

9. A process for electroplating a work according to claim 8, wherein said ring-shaped work is a ring-shaped bonded magnet.

10. A ring-shaped bonded magnet having a plated film on the entire surface thereof, wherein the thickness of said plated film formed on the outer surface is equal to or smaller than that of said plated film formed on the inner surface, and the variability of thickness of said plated film from portion to portion of the outer and inner surfaces is equal to or smaller than 25 %.

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